

Title (en)  
TIN ALLOY SOLDER COMPOSITIONS

Title (de)  
LÖTZUSAMMENSETZUNGEN AUS ZINNLEGIERUNG

Title (fr)  
COMPOSITIONS DE BRASURE A BASE D'ALLIAGE D'ETAIN

Publication  
**EP 1880032 A4 20090304 (EN)**

Application  
**EP 06759560 A 20060511**

Priority  
• US 2006018235 W 20060511  
• US 67986905 P 20050511

Abstract (en)  
[origin: WO2006122240A2] A lead-free and bismuth-free solder alloy composition for electronic assembly applications having reduced toxicity. The alloy composition comprises about 0.01% to about 4.5% silver; about 0.01% to about 3% copper; about 0.002% to about 5.0% antimony; about 85% to about 99% tin and about 0.002% to about 1% of either nickel or cobalt. The alloy composition has a melting temperature of about 217° C, with superior wetting and mechanical strength making the alloy composition well suited for electronic circuit board manufacture and lead less component bumping or column arrays, and replacement of conventional tin-lead solders.

IPC 8 full level  
**B23K 35/26** (2006.01); **C22C 13/00** (2006.01); **C22C 13/02** (2006.01)

CPC (source: EP US)  
**B23K 35/0244** (2013.01 - EP US); **B23K 35/262** (2013.01 - EP US); **C22C 13/00** (2013.01 - EP US); **C22C 13/02** (2013.01 - EP US); **B23K 2101/36** (2018.07 - EP US)

Citation (search report)  
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DOCDB simple family (publication)  
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